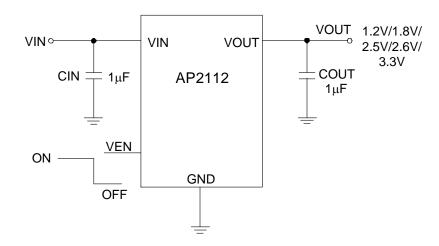


Typical Applications Circuit (Note 4)

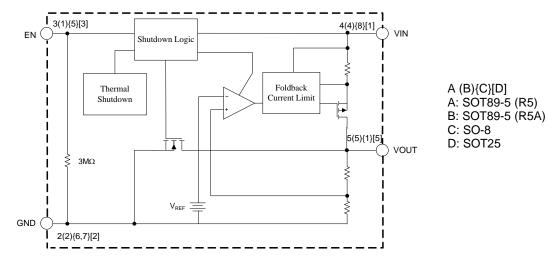


Note 4: It is recommended to use X7R or X5R dielectric capacitor if 1.0µF ceramic capacitor is selected as input/output capacitors.

Pin Descriptions

	Pin Number		Din Nama	Formation	
SOT25	SOT89-5	SO-8	Pin Name	Function	
1	4	8	VIN	Input Voltage	
2	2	6, 7	GND	GND	
	3 (R5)	_		Chip Enable, H – normal work, L – shutdown output	
3	1 (R5A)	5	EN		
	1 (R5)				
_	3 (R5A)	2, 3, 4	NC	No Connection	
5	5	1	VOUT	Output Voltage	

Functional Block Diagram





Absolute Maximum Ratings (Note 5)

Symbol	Parameter	Rat	ing	Unit
Vcc	Power Supply Voltage	6.5		V
TJ	Operating Junction Temperature Range	+1	50	°C
T _{STG}	Storage Temperature Range	-65 to	+150	°C
T _{LEAD}	Lead Temperature (Soldering, 10 Seconds)	+260		°C
		SOT25	184	
θ_{JA}	Thermal Resistance (Junction to Ambient)(No Heatsink)	SO-8	114	°C/W
			120	
_	ESD (Machine Model)	40	400	
_	ESD (Human Body Model)	40	4000	

Note 5: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V _{IN}	Supply Voltage	2.5	6.0	V
T _A	Ambient Operation Temperature Range	-40	+85	°C



Electrical Characteristics

AP2112-1.2 Electrical Characteristics (@ $V_{IN} = 2.5V$, $C_{IN} = 1.0 \mu F$ (Ceramic), $C_{OUT} = 1.0 \mu F$ (Ceramic), Typical $T_A = +25 ^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
Vouт	Output Voltage	$V_{IN} = 2.5V, 1mA \le I_{C}$	_{DUT} ≤ 30mA	V _{OUT} *98.5%	1.2	V _{OUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 2.5V, V_{OUT} = 1$.182V to 1.218V	600	_	_	mA
(ΔV _{ΟυΤ} /V _{ΟυΤ})/ΔΙ _{ΟυΤ}	Load Regulation	$V_{IN} = 2.5V, 1mA \le I_{C}$	_{OUT} ≤ 600mA	-1	0.2	1	%/A
(ΔV _{OUT} /V _{OUT})/ΔV _{IN}	Line Regulation	2.5V ≤ V _{IN} ≤ 6V, I _{OU}	T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		-	1000	1300	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	1000	1300	mV
		I _{OUT} = 600mA		_	1000	1300	
IQ	Quiescent Current	V _{IN} = 2.5V, I _{OUT} = 0r	mA	_	55	80	μΑ
I _{STD}	Standby Current	V _{IN} = 2.5V, V _{EN} in O	FF mode	_	0.01	1.0	μΑ
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 2.5V, I _{OUT} = 100mA	f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔΤ	Output Voltage Temperature Coefficient	$I_{OUT} = 30\text{mA}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$;	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	_	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV_{RMS}
ViH	V _{EN} High Voltage	Enable logic high, re	gulator on	1.5	_	6.0	.,
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0	_	0.4	V
t _S	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	ΜΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	_
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ_{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
	(3	SOT89-5			47	_	



AP2112-1.8 Electrical Characteristics (@V_{IN} = 2.8V, C_{IN} = 1.0 μ F (Ceramic), C_{OUT} = 1.0 μ F (Ceramic), Typical T_A = +25°C, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
Vouт	Output Voltage	V _{IN} = 2.8V, 1mA ≤ I _O	_{DUT} ≤ 30mA	V _{ОUТ} *98.5%	1.8	V _{ОUТ} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	V _{IN} = 2.8V, V _{OUT} = 1	.773V to 1.827V	600	1	_	mA
(ΔVουτ/Vουτ)/ΔΙουτ	Load Regulation	$V_{OUT} = 1.8V$, $V_{IN} = V$ $1mA \le I_{OUT} \le 600mA$		-1	0.2	1	%/A
(ΔV _{OUT} /V _{OUT})/ΔV _{IN}	Line Regulation	$2.8V \le V_{IN} \le 6V$, I_{OU}	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	500	700	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	500	700	mV
		I _{OUT} = 600mA		_	500	700	
IQ	Quiescent Current	V _{IN} = 2.8V, I _{OUT} = 0r	nA	_	55	80	μΑ
I _{STD}	Standby Current	V _{IN} = 2.8V, V _{EN} in O	FF mode	_	0.01	1.0	μΑ
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	$V_{IN} = 2.8V$, $I_{OUT} = 100mA$	f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔT	Output Voltage Temperature Coefficient	$I_{OUT} = 30\text{mA}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$;	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	_	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV_{RMS}
V _{IH}	V _{EN} High Voltage	Enable logic high, re	egulator on	1.5	1	6.0	V
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0	1	0.4	V
ts	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	МΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ_{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
	(32.13.1311 to 32.00)	SOT89-5			47	_	



AP2112-2.5 Electrical Characteristics (@V_{IN} = 3.5V, C_{IN} = 1.0 μ F (Ceramic), C_{OUT} = 1.0 μ F (Ceramic), Typical T_A = +25°C, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
V _{ОUТ}	Output Voltage	V _{IN} = 3.5V, 1mA ≤ I ₀	_{OUT} ≤ 30mA	V _{ОUТ} *98.5%	2.5	V _{OUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 3.5V$, $V_{OUT} = 2.463V$ to 2.5	537V	600	-	_	mA
(ΔV _{ΟυΤ} /V _{ΟυΤ})/ΔΙ _{ΟυΤ}	Load Regulation	$V_{OUT} = 2.5V$, $V_{IN} = V$ $1mA \le I_{OUT} \le 600mA$		-1	0.2	1	%/A
$(\Delta V_{OUT}/V_{OUT})/\Delta V_{IN}$	Line Regulation	3.5V ≤ V _{IN} ≤ 6V, I _{OU}	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
IQ	Quiescent Current	V _{IN} = 3.5V, I _{OUT} = 0r	mA	_	55	80	μΑ
I _{STD}	Standby Current	V _{IN} = 3.5V, V _{EN} in O	FF mode	_	0.01	1.0	μΑ
2022	PSRR Power Supply Rejection Ratio		f = 100Hz	_	65	_	
PSRR			f = 1KHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔT	Output Voltage Temperature Coefficient	$I_{OUT} = 30 \text{mA}$ $T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C}$;	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	_	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV_{RMS}
V _{IH}	V _{EN} High Voltage	Enable logic high, re	egulator on	1.5	1	6.0	V
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0		0.4	V
ts	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	ΜΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
	(50.15.15) (5 50.05)	SOT89-5		_	47	_	



AP2112-2.6 Electrical Characteristics (@V_{IN} = 3.6V, C_{IN} = 1.0μF (Ceramic), C_{OUT} = 1.0μF (Ceramic), Typical T_A = +25°C, unless otherwise specified (Note 6))

Symbol	Parameter	Condit	ions	Min	Тур	Max	Unit
V _{ОUТ}	Output Voltage	$V_{IN} = 3.6V, 1mA \le I_{C}$	_{DUT} ≤ 30mA	V _{ОUТ} *98.5%	2.6	V _{OUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 3.6V$, $V_{OUT} = 2.561V$ to 2.0	639V	600	1	_	mA
(ΔV _{OUT} /V _{OUT})/ΔI _{OUT}	Load Regulation	$V_{OUT} = 2.6V$, $V_{IN} = V$ $1mA \le I_{OUT} \le 600mA$		-1	0.2	1	%/A
(ΔV _{OUT} /V _{OUT})/ΔV _{IN}	Line Regulation	3.6V ≤ V _{IN} ≤ 6V, I _{OU}	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
IQ	Quiescent Current	$V_{IN} = 3.6V$, $I_{OUT} = 0$ r	mA	_	55	80	μΑ
I _{STD}	Standby Current	V _{IN} = 3.6V, V _{EN} in O	FF mode	_	0.01	1.0	μΑ
2022	PSRR Power Supply Rejection Ratio Rip V _{IN} I _{OU}		f = 100Hz	_	65	_	
PSRR			f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔT	Output Voltage Temperature Coefficient	$I_{OUT} = 30 \text{mA}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	<u> </u>	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	_	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV_{RMS}
V _{IH}	V _{EN} High Voltage	Enable logic high, re	egulator on	1.5	1	6.0	V
VIL	V _{EN} Low Voltage	Enable logic low, re	gulator off	0	1	0.4	V
ts	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	МΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	30
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
	(2	SOT89-5			47		



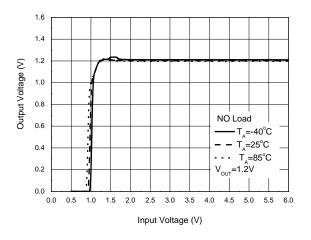
AP2112-3.3 Electrical Characteristics (@V_{IN} = 4.3V, C_{IN} = 1.0 μ F (Ceramic), C_{OUT} = 1.0 μ F (Ceramic), Typical T_A = +25°C, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
V _{ОUТ}	Output Voltage	V _{IN} = 4.3V, 1mA ≤ I _O	_{DUT} ≤ 30mA	V _{ОUТ} *98.5%	3.3	V _{ОUТ} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 4.3V, V_{OUT} = 3$	3.251V to 3.350V	600	-	_	mA
(ΔV _{OUT} /V _{OUT})/ΔΙ _{ΟUT}	Load Regulation	V _{IN} = 4.3V, 1mA ≤ I _O	_{DUT} ≤ 600mA	-1	0.2	1	%/A
(ΔV _{OUT} /V _{OUT})/ΔV _{IN}	Line Regulation	4.3V≤ V _{IN} ≤ 6V, I _{OU} -	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
IQ	Quiescent Current	V _{IN} = 4.3V, I _{OUT} = 0r	mA	_	55	80	μΑ
I _{STD}	Standby Current	V _{IN} = 4.3V, V _{EN} in O	FF mode	_	0.01	1.0	μΑ
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 4.3V, I _{OUT} = 100mA	f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔΤ	Output Voltage Temperature Coefficient	$I_{OUT} = 30\text{mA}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$;	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	_	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV_{RMS}
ViH	V _{EN} High Voltage	Enable logic high, re	egulator on	1.5		6.0	.,
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0		0.4	V
t _S	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	МΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	_ 96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
	(33.70101110 0400)	SOT89-5		_	47	_	

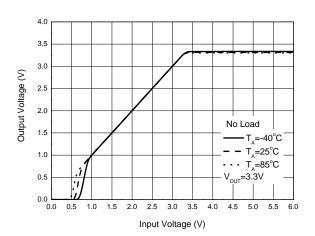


Performance Characteristics

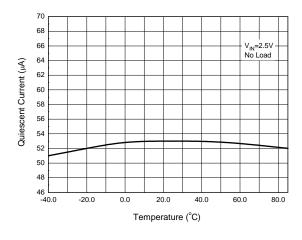
Output Voltage vs. Input Voltage



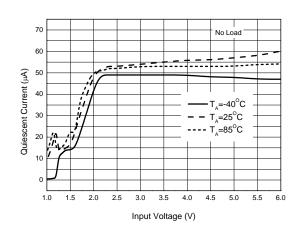
Output Voltage vs. Input Voltage



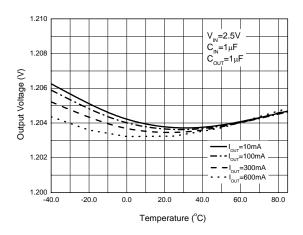
Quiescent Current vs. Temperature



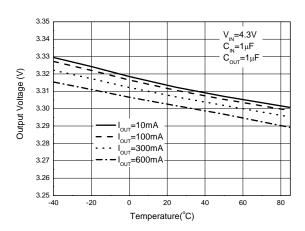
Quiescent Current vs. Input Voltage



Output Voltage vs. Temperature



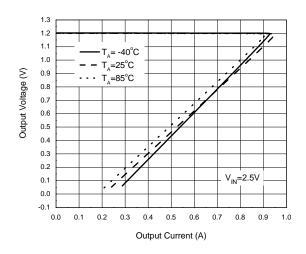
Output Voltage vs. Temperature



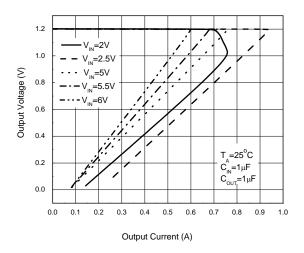


Performance Characteristics (Cont.)

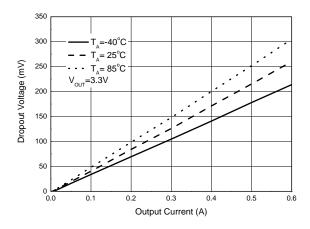
Output Voltage vs. Output Current



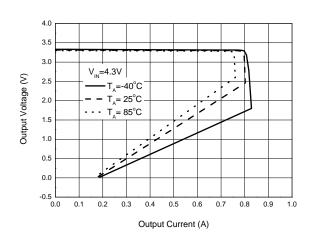
Output Voltage vs. Output Current



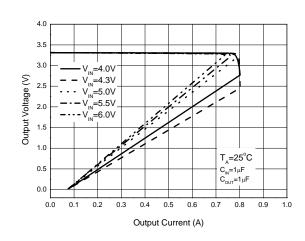
Dropout Voltage vs. Output Current



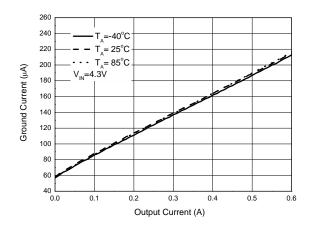
Output Voltage vs. Output Current



Output Voltage vs. Output Current



Ground Current vs. Output Current

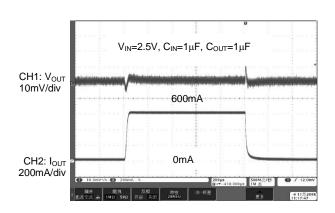




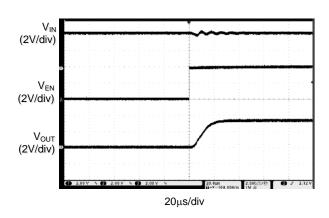
Performance Characteristics (Cont.)

PSRR vs. Frequency

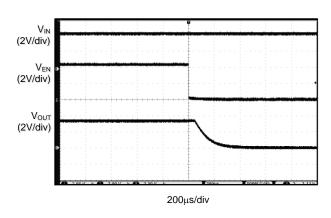
Load Transient



Enable On

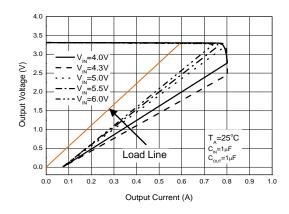


Enable Off



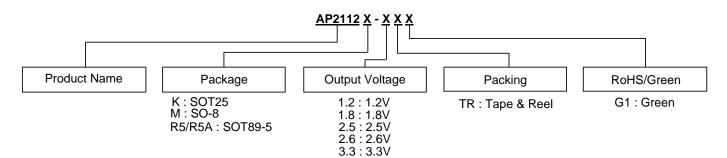
Application Note

In some unusual applications where a current load could be present at the output before the part is enabled the fold back current limiting may prevent the part from starting. Applications with multiple supplies or negative supplies need to be evaluated for this possibility. Product testing where a current source is applied before the part is enabled could be another area of concern. With a normal load as shown below there is no interference of the fold back current limiting circuit.





Ordering Information



Package	Temperature Range	Condition	Part Number	Marking ID	Packing
		1.2V	AP2112K-1.2TRG1	G3L	3000/7"/Tape & Reel
		1.8V	AP2112K-1.8TRG1	G3M	3000/7"/Tape & Reel
SOT25	-40 to +85°C	2.5V	AP2112K-2.5TRG1	G3N	3000/7"/Tape & Reel
		2.6V	AP2112K-2.6TRG1	G5N	3000/7"/Tape & Reel
		3.3V	AP2112K-3.3TRG1	G3P	3000/7"/Tape & Reel
		1.2V	AP2112M-1.2TRG1	2112M-1.2G1	4000/13"/Tape & Reel
		1.8V	AP2112M-1.8TRG1	2112M-1.8G1	4000/13"/Tape & Reel
SO-8	-40 to +85°C	2.5V	AP2112M-2.5TRG1	2112M-2.5G1	4000/13"/Tape & Reel
		2.6V	AP2112M-2.6TRG1	2112M-2.6G1	4000/13"/Tape & Reel
		3.3V	AP2112M-3.3TRG1	2112M-3.3G1	4000/13"/Tape & Reel
		1.2V(R5)	AP2112R5-1.2TRG1	G37D	1000/7"/Tape & Reel
		1.8V(R5)	AP2112R5-1.8TRG1	G37E	1000/7"/Tape & Reel
SOT89-5	-40 to +85°C	2.5V(R5)	AP2112R5-2.5TRG1	G37F	1000/7"/Tape & Reel
		2.6V(R5)	AP2112R5-2.6TRG1	G13F	1000/7"/Tape & Reel
		3.3V(R5)	AP2112R5-3.3TRG1	G37G	1000/7"/Tape & Reel
		1.2V(R5A)	AP2112R5A-1.2TRG1	G33C	1000/7"/Tape & Reel
		1.8V(R5A)	AP2112R5A-1.8TRG1	G33E	1000/7"/Tape & Reel
SOT89-5	-40 to +85°C	2.5V(R5A)	AP2112R5A-2.5TRG1	G28G	1000/7"/Tape & Reel
		2.6V(R5A)	AP2112R5A-2.6TRG1	G13E	1000/7"/Tape & Reel
		3.3V(R5A)	AP2112R5A-3.3TRG1	G28H	1000/7"/Tape & Reel



Marking Information

(1) SOT25



: Logo XXX : Marking ID (See Ordering Information)

(2) SO-8



First line: Logo and Marking ID Second line: Date Code Y: Year

WW: Work Week of Molding

A: Assembly House Code XX: 7th and 8th Digits of Batch Number

(3) SOT89-5



First Line: Logo and Marking ID Second line: Date Code Y: Year

WW: Work Week of Molding

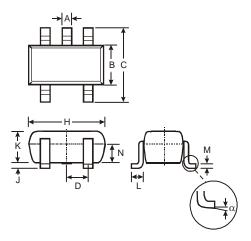
A: Assembly House Code XX: 7th and 8th Digits of Batch Number



Package Outline Dimensions (Previously identified as SOT-23-5 for this product)

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT25

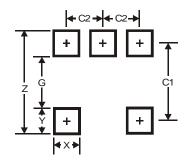


	SOT	25					
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
C	2.70	3.00	2.80				
D	-	-	0.95				
Η	2.90	3.10	3.00				
7	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
M	0.10	0.20	0.15				
N	0.70	0.80	0.75				
α	α 0° 8° -						
All D	imensi	ons in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT25



Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Υ	0.80
C1	2.40
C2	0.95

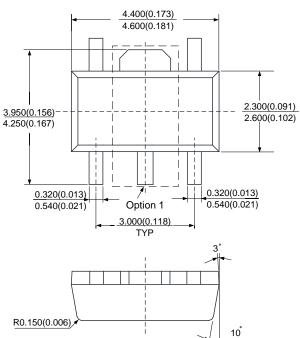
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

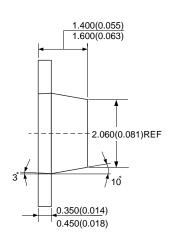
Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

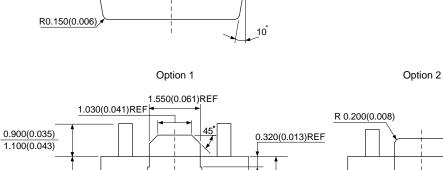


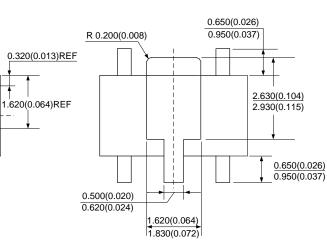
$\textbf{Package Outline Dimensions} \ \, \textbf{(All dimensions in mm.)} \ \, \textbf{(Previously identified as SOT-89-5 for this product)}$

SOT89-5









2.210(0.087)REF

0.480(0.019)

TYP

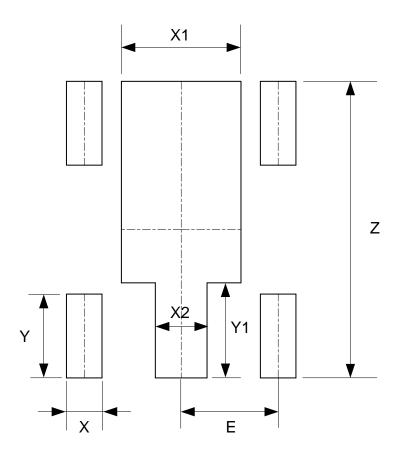
1.500(0.059) 1.800(0.071)

0.900(0.035) 1.100(0.043)



Suggested Pad Layout (Previously identified as SOT-89-5 for this product)

SOT89-5



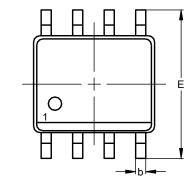
Dimensions	Z	Х	X1	X2	Υ	Y1	Е
Dimensions	(mm)/(inch)						
Value	4.600/0.181	0.550/0.022	1.850/0.073	0.800/0.031	1.300/0.051	1.475/0.058	1.500/0.059

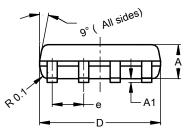


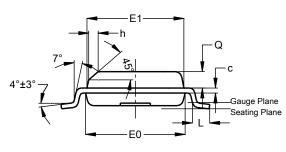
Package Outline Dimensions (Previously identified as SOIC-8 for this product)

Please see http://www.diodes.com/package-outlines.html for the latest version.







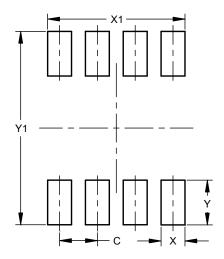


SO-8			
Dim	Min	Max	Тур
Α	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
С	0.15	0.25	0.20
D	4.85	4.95	4.90
Е	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
е			1.27
h	-		0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)	
С	1.27	
Х	0.802	
X1	4.612	
Υ	1.505	
Y1	6.50	

Note:

The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Note:

For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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